



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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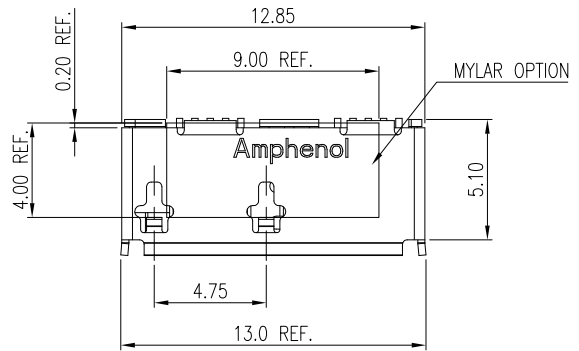
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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The marking on this product doesn't contain environmental hazardous material and must follow one or more specifications per Material Specification SS-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant or per IEC 61249-2-21 for Halogen Free compliant.

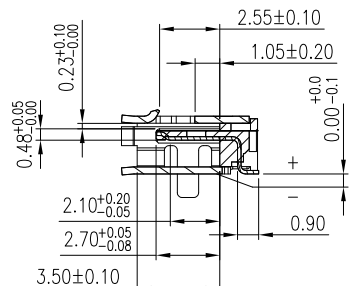
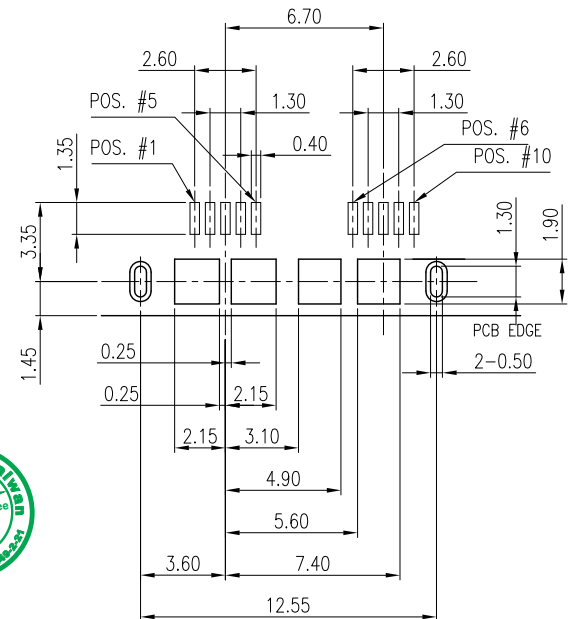
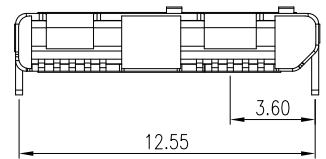
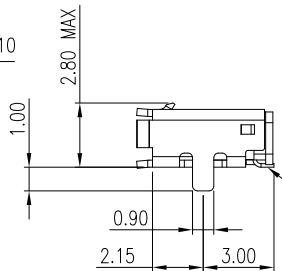
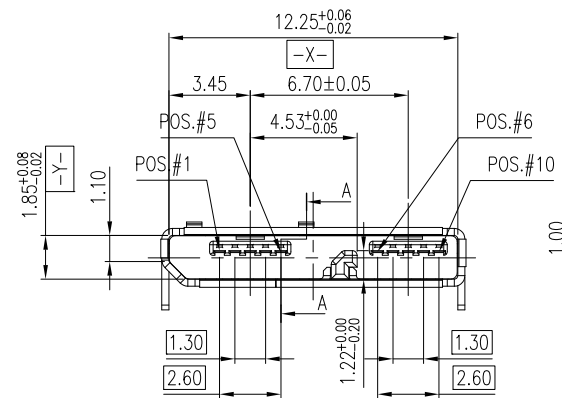
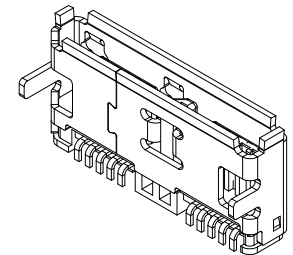
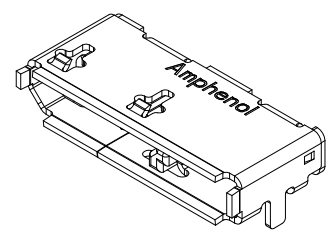
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	BY
AX1		UNAPPROVAL REVISION	05/27/2010	Sondra Sang



PART NUMBER:  
GSB3 43K 3 3 X HR

CONTACT FINISH:  
3: 30μ" GOLD

VARIATION CODE  
BLANK: STANDARD T&R PACKING  
A: W/ MYLAR, T&R PACKING



RECOMMENDED PCB LAYOUT- TOP VIEW  
(GENERAL TOLERANCE: ±0.05)

- NOTES:
- HOUSING: HIGH TEMP. THERMOPLASTIC, UL 94V-0, COLOR- BLACK
  - CONTACT: COPPER ALLOY, 0.15mm THICKNESS, 30μ" MIN. GOLD PLATED ON CONTACT AREA, GOLD FLASH PLATED ON SOLDERING TAIL, 80μ" MIN. NICKEL UNDER-PLATED OVERALL
  - METAL SHELL: STAINLESS, 0.3mm THICKNESS, GOLD FLASH PLATED ON THE SOLDERING TABS
  - MYLAR: 4.0 x 9.0 mm
  - THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2002/95/EC FOR RoHS AND PER IEC 61249-2-21 FOR HALOGEN FREE COMPLIANT.

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30	DRAWN Sondra Sang	05/27/2010	USB 3.0 CONNECTOR MICRO_B, RECEPTACLE R/A SMT, SHELL DIP TYPE	mm	A3	GSB3 43K 33X HR
X.X ±0.20	CHECKED Chenny Yeh	05/27/2010				
X.XX ±0.20	APPROVED Hank Hsu	05/27/2010				
X.XXX ±0.10	DWG TYPE CUST DWG	PROJECT CODE T503				
ANGULAR ±1°				SCALE NA	SHEET 1 OF 1	DWG No. GSB343K33HR
UNLESS OTHERWISE SPECIFIED						REV. AX1